

Caution/Notice

Caution

- Storage and Operation Conditions
- Rating
 1. Operating Voltage
 2. Operating Temperature, Self-generated Heat, and Load Reduction at High-frequency Voltage Condition
 3. Fail-safe
 4. Test Condition for AC Withstanding Voltage
 - (1) Test Equipment
 - (2) Voltage Applied Method
- Soldering and Mounting
 1. Vibration and Impact
 2. Circuit Board Material
 3. Land Layout for Cropping PC Board
 4. Reflow Soldering
 5. Flow Soldering
 6. Correction with a Soldering Iron
 7. Washing
 8. Handling

Notice

- Rating
 1. Capacitance Change of Capacitor
 2. Performance Check by Equipment
- Soldering and Mounting
 1. Construction of Board Pattern
 2. Mounting of Chips
 3. Soldering
 - (1) Limit of losing effective area of the terminations and conditions needed for soldering.
 - (2) Flux Application
 - (3) Solder
 4. Cleaning
 5. Resin Coating

⚠ Caution

■ Storage and Operation Conditions

Do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. In addition, avoid exposure to moisture. Before cleaning, bonding or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed 5 to 40 degrees centigrade and 20 to 70%. Use capacitors within 6 months of delivery. Check the solderability after 6 months or more.

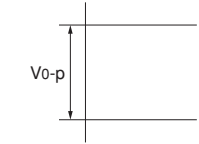
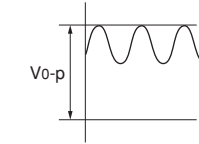
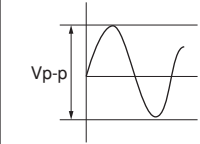
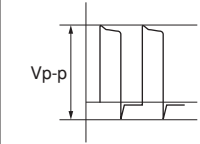
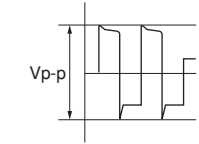
■ Rating

1. Operating Voltage

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the V_{p-p} value of the applied voltage or the V_{o-p} which contains DC bias within the rated voltage range.

When the voltage is applied to the circuit, starting or stopping may generate irregular voltage for a transit period because of resonance or switching. Be sure to use a capacitor with a rated voltage range that includes these irregular voltages.

When DC-rated capacitors are to be used in input circuits from a commercial power source (AC filter), be sure to use Safety Certified Capacitors because various regulations for withstanding voltage or impulses, established for all equipment, should be taken into consideration.

Voltage	DC Voltage	DC+AC Voltage	AC Voltage	Pulse Voltage (1)	Pulse Voltage (2)
Positional Measurement					

2. Operating Temperature, Self-generated Heat, and Load Reduction at High-frequency Voltage Condition

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range.

Be sure to take into account the heat generated by the capacitor itself. When the capacitor is used in a high-frequency voltage, pulse voltage, it may self-generate heat due to dielectric loss.

(1) In the case of X7R, X7T char.

Applied voltage should be the load such as self-generated heat is within 20°C on the condition of atmosphere temperature 25°C. When measuring, use a thermocouple of small thermal capacity -K of $\phi 0.1$ mm in conditions where the capacitor is not affected by radiant heat from other components or surrounding ambient fluctuations. Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. (Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.)

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Caution

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(2) In case of C0G, U2J char.

Due to the low self-heating characteristics of low-dissipation capacitors, the allowable electric power of these capacitors is generally much higher than that of X7R characteristic capacitors.

When a high frequency voltage that causes 20°C self-heating to the capacitor is applied, it will exceed the capacitor's allowable electric power.

The frequency of the applied sine wave voltage should be less than 500kHz (less than 100kHz in the case of rated voltage: DC3.15kV). The applied voltage should be less than the value shown in figure below.

In the case of non-sine wave that includes a harmonic frequency, please contact our sales representatives or product engineers. Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. (Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.)

<C0G char., Rated Voltage: DC3.15kV>

The capacitors less than 22pF can be applied maximum 4.0kV peak to peak at 100kHz or less only for the ballast or the resonance usage in the LCD backlight inverter circuit.

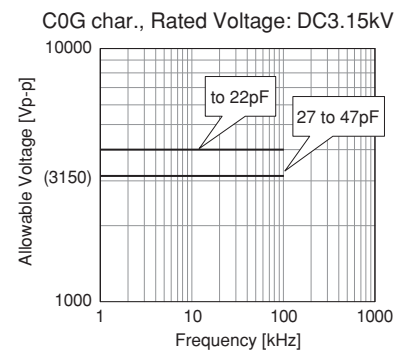
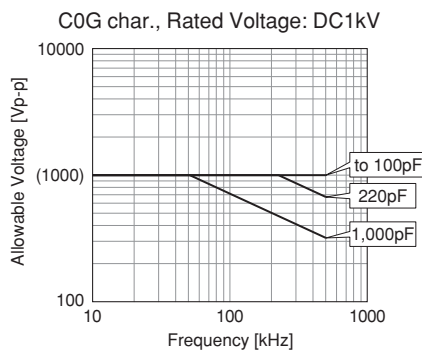
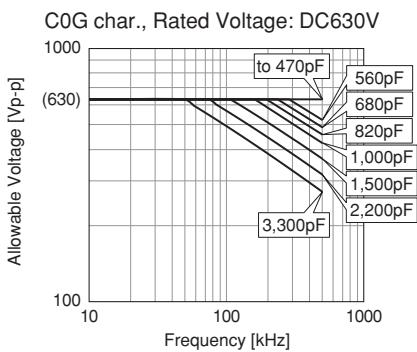
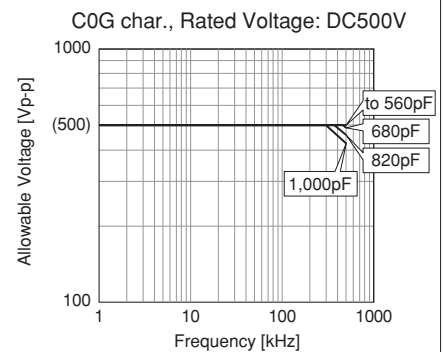
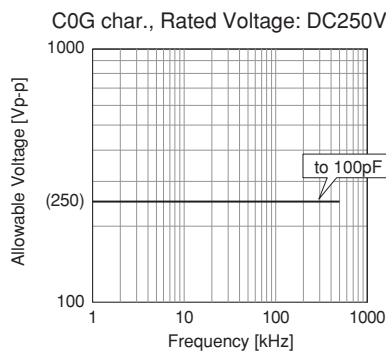
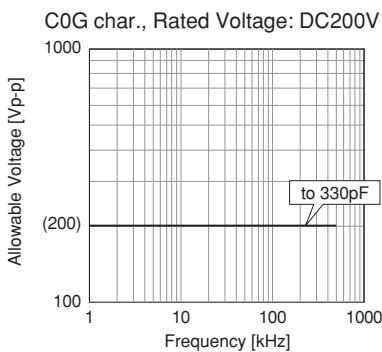
<Capacitor Selection Tool>

We are also offering free software/the capacitor selection tool: "Murata Medium Voltage Capacitors Selection Tool by Voltage Form," which will assist you in selecting a suitable capacitor.

The software can be downloaded from Murata's Website. (http://www.murata.com/products/design_support/mmcsv/index.html).

By inputting capacitance values and the applied voltage waveform of the specific capacitor series, this software will calculate the capacitor's power consumption and list suitable capacitors (non-sine wave is also available).

The temperature of the surface of capacitor: 125°C or less (including self-heating)



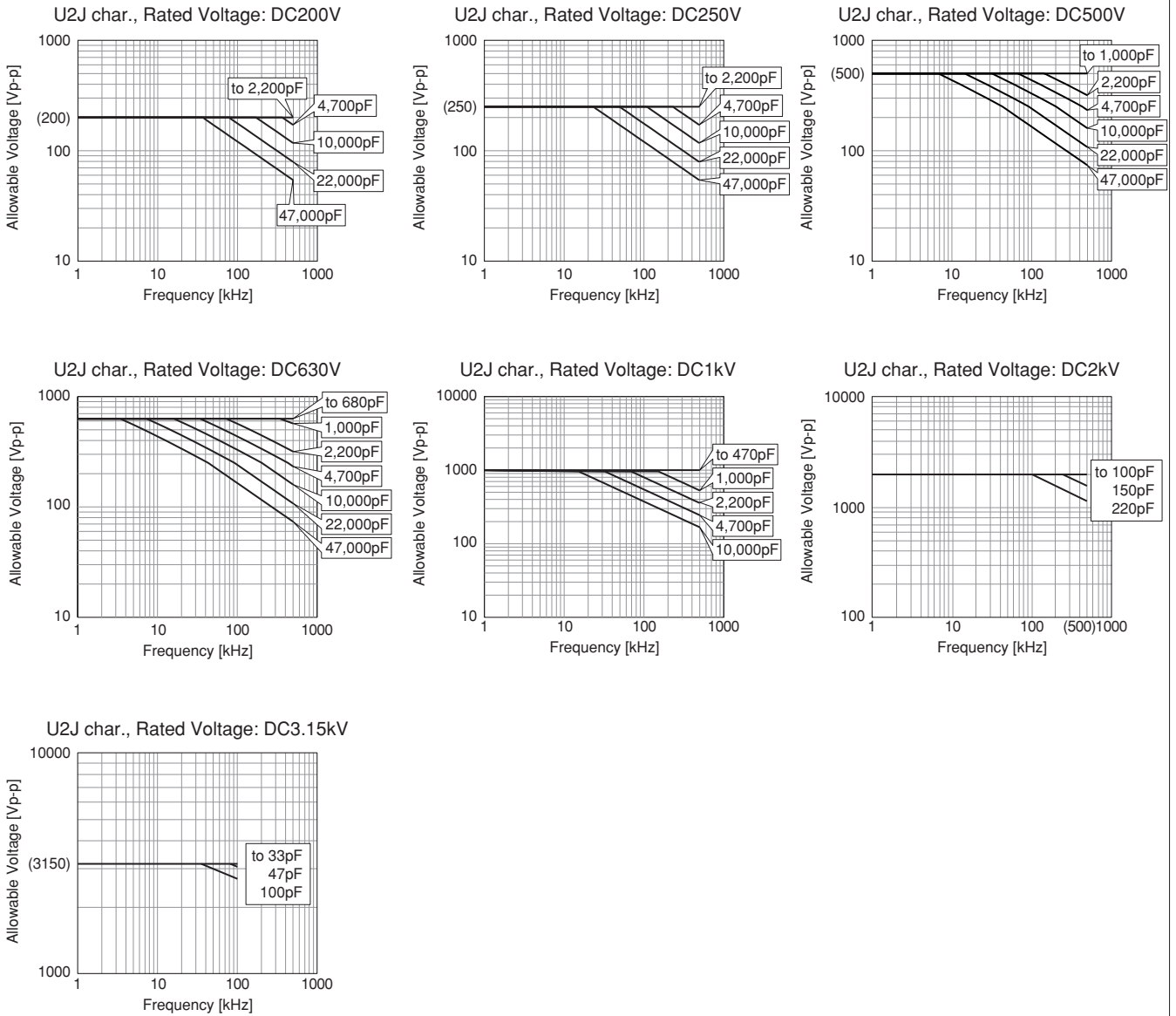
The sine-wave frequency VS allowable voltage

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Caution

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The temperature of the surface of capacitor: 125°C or less (including self-heating)

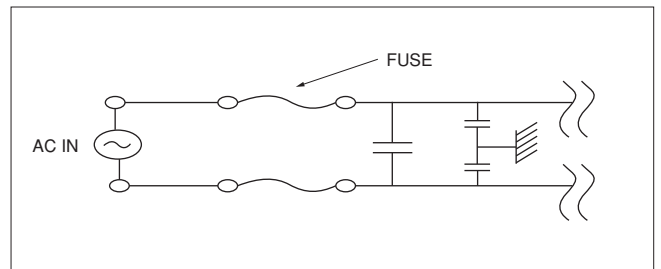


The sine-wave frequency VS allowable voltage

3. Fail-safe

Failure of a capacitor may result in a short circuit. Be sure to provide an appropriate fail-safe function such as a fuse on your product to help eliminate possible electric shock, fire, or fumes.

Please consider using fuses on each AC line if the capacitors are used between the AC input lines and earth (line bypass capacitors), to prepare for the worst case, such as a short circuit.



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⚠ Caution

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4. Test Condition for AC Withstanding Voltage

(1) Test Equipment

Tests for AC withstanding voltage should be made with equipment capable of creating a wave similar to a 50/60 Hz sine wave.

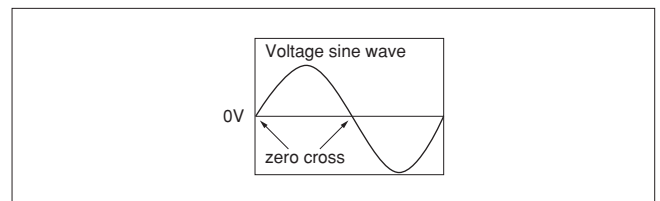
If the distorted sine wave or overload exceeding the specified voltage value is applied, a defect may be caused.

*ZERO CROSS is the point where voltage sine wave passes 0V.

- See the figure at right -

(2) Voltage Applied Method

The capacitor's leads or terminals should be firmly connected to the output of the withstanding voltage test equipment, and then the voltage should be raised from near zero to the test voltage. If the test voltage is applied directly to the capacitor without raising it from near zero, it should be applied with the zero cross.* At the end of the test time, the test voltage should be reduced to near zero, and then the capacitor's leads or terminals should be taken off the output of the withstanding voltage test equipment. If the test voltage is applied directly to the capacitor without raising it from near zero, surge voltage may occur and cause a defect.



■ Soldering and Mounting

1. Vibration and Impact

Do not expose a capacitor to excessive shock or vibration during use.

2. Circuit Board Material

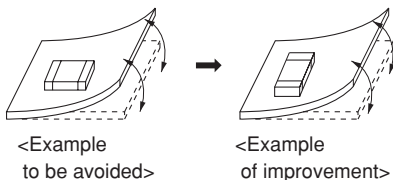
It is possible for the chip to crack by the expansion and shrinkage of a metal board.

Please contact us if you want to use our ceramic capacitors on a metal board such as Aluminum.

3. Land Layout for Cropping PC Board

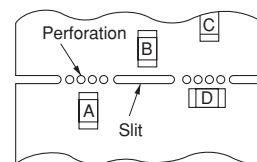
Choose a mounting position that minimizes the stress imposed on the chip during flexing or bending of the board.

[Component Direction]



Locate chip horizontal to the direction in which stress acts.

[Chip Mounting Close to Board Separation Point]



Chip arrangement Worst A>C>B~D Best

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Caution

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4. Reflow Soldering

- When components are exposed to sudden heat, their mechanical strength can be decreased due to the extreme temperature changes which can cause flexing and result in internal mechanical damage, which will cause the parts to fail. In order to prevent mechanical damage, preheating is required for both the components and the PCB board. Preheating conditions are shown in Table 1. It is required to keep the temperature differential between the soldering and the components surface (ΔT) as small as possible.
- Solderability of Tin plating termination chips might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chips before use.
- When components are immersed in solvent after mounting, be sure to maintain the temperature difference (ΔT) between the component and solvent within the range shown in the Table 1.

Table 1

Part Number	Temperature Differential
G□□18/21/31	$\Delta T \leq 190^\circ\text{C}$
G□□32/42/43/52/55	$\Delta T \leq 130^\circ\text{C}$

Recommended Conditions

	Pb-Sn Solder		Lead Free Solder
	Infrared Reflow	Vapor Reflow	
Peak Temperature	230-250°C	230-240°C	240-260°C
Atmosphere	Air	Air	Air or N ₂

Pb-Sn Solder: Sn-37Pb

Lead Free Solder: Sn-3.0Ag-0.5Cu

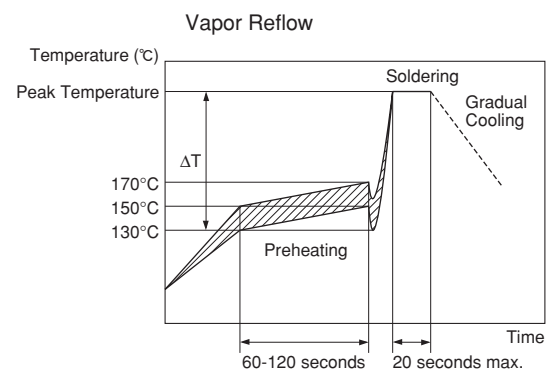
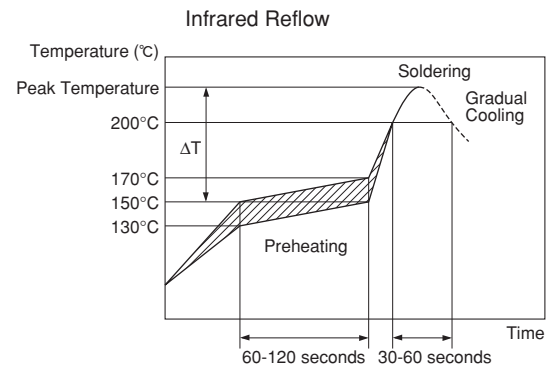
Optimum Solder Amount for Reflow Soldering

- Overly thick application of solder paste results in excessive solder fillet height. This makes the chip more susceptible to mechanical and thermal stress on the board and may cause cracked chips.
- Too little solder paste results in a lack of adhesive strength on the outer electrode, which may result in chips breaking loose from the PCB.
- Make sure the solder has been applied smoothly to the end surface to a height of 0.2mm min.

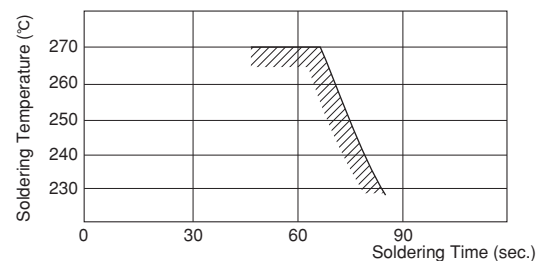
Inverting the PCB

Make sure not to impose an abnormal mechanical shock on the PCB.

[Standard Conditions for Reflow Soldering]

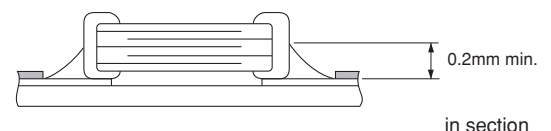


[Allowable Soldering Temperature and Time]



In the case of repeated soldering, the accumulated soldering time must be within the range shown above.

[Optimum Solder Amount for Reflow Soldering]



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⚠ Caution

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5. Flow Soldering

- When components are exposed to sudden heat, their mechanical strength can be decreased due to the extreme temperature changes which can cause flexing and result in internal mechanical damage, which will cause the parts to fail. Additionally, an excessively long soldering time or high soldering temperature results in leaching by the outer electrodes, causing poor adhesion or a reduction in capacitance value due to loss of contact between electrodes and end termination.
- In order to prevent mechanical damage, preheating is required for both the components and the PCB board. Preheating conditions are shown in Table 2. It is required to keep temperature differential between the soldering and the components surface (ΔT) as small as possible.
- When components are immersed in solvent after mounting, be sure to maintain the temperature difference between the component and solvent within the range shown in Table 2.
Do not apply flow soldering to chips not listed in Table 2.

Table 2

Part Number	Temperature Differential
G□□18/21/31	$\Delta T \leq 150^\circ\text{C}$

Recommended Conditions

	Pb-Sn Solder	Lead Free Solder
Peak Temperature	240-250°C	250-260°C
Atmosphere	Air	N ₂

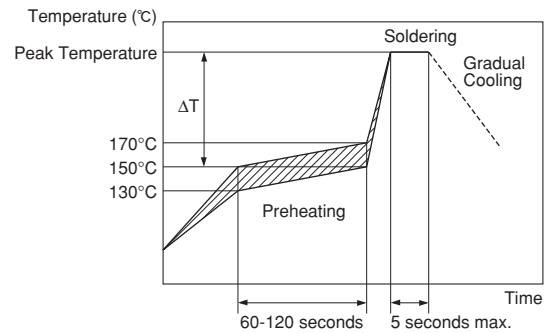
Pb-Sn Solder: Sn-37Pb

Lead Free Solder: Sn-3.0Ag-0.5Cu

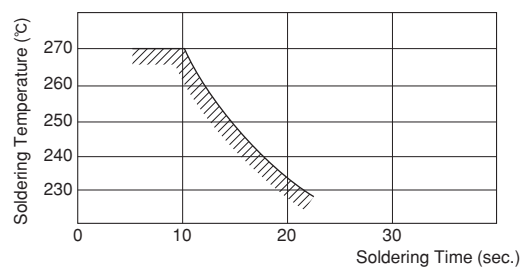
● Optimum Solder Amount for Flow Soldering

The top of the solder fillet should be lower than the thickness of components. If the solder amount is excessively large, the risk of cracking is higher during board bending or under any other stressful conditions.

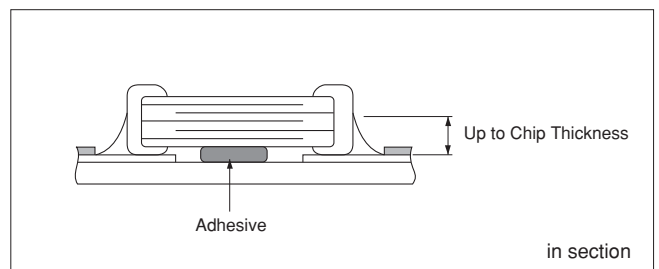
[Standard Conditions for Flow Soldering]



[Allowable Soldering Temperature and Time]



In the case of repeated soldering, the accumulated soldering time must be within the range shown above.



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Caution

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6. Correction with a Soldering Iron

- When sudden heat is applied to the components by use of a soldering iron, the mechanical strength of the components will decrease because the extreme temperature change causes deformations inside the components.

In order to prevent mechanical damage to the components, preheating is required for both the components and the PCB board.

Preheating conditions, (The "Temperature of the Soldering Iron Tip", "Preheating Temperature," "Temperature Differential" between iron tip and the

components and the PCB), should be within the conditions of table 3.

It is required to keep the temperature differential between the soldering Iron and the component's surface (ΔT) as small as possible.

After soldering, do not allow the component/PCB to cool down rapidly.

The operating time for the re-working should be as short as possible. When re-working time is too long, it may cause solder leaching, in turn causing a reduction of the adhesive strength of the terminations.

Table 3

Part Number	Temperature of Soldering Iron tip	Preheating Temperature	Temperature Differential (ΔT)	Atmosphere
G□□18/21/31	350°C max.	150°C min.	$\Delta T \leq 190^\circ\text{C}$	air
G□□32/42/43/52/55	280°C max.	150°C min.	$\Delta T \leq 130^\circ\text{C}$	air

*Applicable for both Pb-Sn and Lead Free Solder.

Pb-Sn Solder: Sn-37Pb

Lead Free Solder: Sn-3.0Ag-0.5Cu

- Optimum Solder Amount when re-working Using a Soldering Iron

For sizes smaller than G□□18, the top of the solder fillet should be lower than 2/3 of the thickness of the component or 0.5mm whichever is smaller.

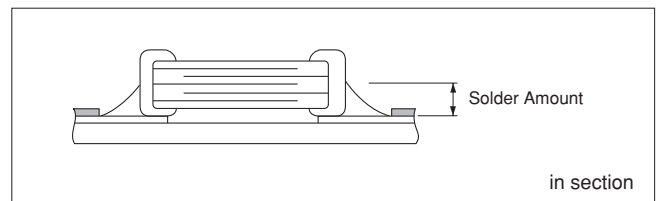
For sizes larger than G□□21, the top of the solder fillet should be lower than 2/3 of the thickness of the component.

If the solder amount is excessive, the risk of cracking is higher during board bending or under any other stressful conditions.

A Soldering iron $\phi 3\text{mm}$ or smaller should be used.

It is also necessary to keep the soldering iron from touching the components during the re-work.

Solder wire with $\phi 0.5\text{mm}$ or smaller is required for soldering.



7. Washing

Excessive output of ultrasonic oscillation during cleaning causes PCBs to resonate, resulting in cracked chips or broken solder. Take note not to vibrate PCBs.

8. Handling

Do not directly touch the chip capacitor, especially the ceramic body. Residue from hands/fingers may create a short circuit environment.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND FUMING WHEN THE PRODUCT IS USED.

Notice

Rating

1. Capacitance Change of Capacitor

(1) In the case of X7R, X7T char.

Capacitors have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor is left on for a long time. Moreover, capacitance might change greatly depending on the surrounding temperature or an applied voltage. Therefore, it is not likely to be suitable for use in a time constant circuit. Please contact us if you need detailed information.

(2) In the case of any char. except X7R, X7T

Capacitance might change a little depending on the surrounding temperature or an applied voltage. Please contact us if you intend to use this product in a strict time constant circuit.

2. Performance Check by Equipment

Before using a capacitor, check that there is no problem in the equipment's performance and the specifications.

Generally speaking, CLASS 2 (X7R, X7T char.) ceramic capacitors have voltage dependence characteristics and temperature dependence characteristics in capacitance. Therefore, the capacitance value may change depending on the operating condition in the equipment.

Accordingly, be sure to confirm the apparatus performance of receiving influence in a capacitance value change of a capacitor, such as leakage current and noise suppression characteristics.

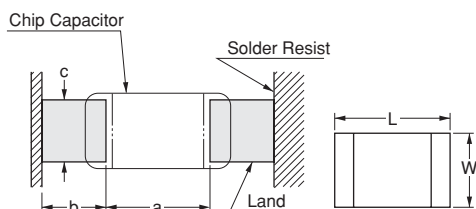
Moreover, check the surge-proof ability of a capacitor in the equipment, if needed, because the surge voltage may exceed the specific value by the inductance of the circuit.

Soldering and Mounting

1. Construction of Board Pattern

After installing chips, if solder is excessively applied to the circuit board, mechanical stress will cause destruction resistance characteristics to lower. To prevent this, be extremely careful in determining shape and dimension before designing the circuit board diagram.

Construction and Dimensions of Pattern (Example)



Flow Soldering

L×W	a	b	c
1.6×0.8	0.6-1.0	0.8-0.9	0.6-0.8
2.0×1.25	1.0-1.2	0.9-1.0	0.8-1.1
3.2×1.6	2.2-2.6	1.0-1.1	1.0-1.4

Flow soldering: 3.2×1.6 or less available.

Reflow Soldering

L×W	a	b	c
1.6×0.8	0.6-0.8	0.6-0.7	0.6-0.8
2.0×1.25	1.0-1.2	0.6-0.7	0.8-1.1
3.2×1.6	2.2-2.4	0.8-0.9	1.0-1.4
3.2×2.5	2.0-2.4	1.0-1.2	1.8-2.3
4.5×2.0	2.8-3.4	1.2-1.4	1.4-1.8
4.5×3.2	2.8-3.4	1.2-1.4	2.3-3.0
5.7×2.8	4.0-4.6	1.4-1.6	2.1-2.6
5.7×5.0	4.0-4.6	1.4-1.6	3.5-4.8

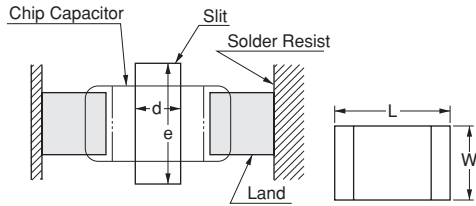
(in mm)

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Notice

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Dimensions of Slit (Example)



L×W	d	e
1.6×0.8	-	-
2.0×1.25	-	-
3.2×1.6	1.0-2.0	3.2-3.7
3.2×2.5	1.0-2.0	4.1-4.6
4.5×2.0	1.0-2.8	3.6-4.1
4.5×3.2	1.0-2.8	4.8-5.3
5.7×2.8	1.0-4.0	4.4-4.9
5.7×5.0	1.0-4.0	6.6-7.1

(in mm)

Preparing the slit helps flux cleaning and resin coating on the back of the capacitor.

However, the length of the slit design should be as short as possible to prevent mechanical damage in the capacitor.

A longer slit design might receive more severe mechanical stress from the PCB.

Recommended slit design is shown in the Table.

Land Layout to Prevent Excessive Solder

	Mounting Close to a Chassis	Mounting with Leaded Components	Mounting Leaded Components Later
Examples to Be Avoided			
Examples of Improvements by the Land Division			

2. Mounting of Chips

● Thickness of adhesives applied

Keep thickness of adhesives applied (50-105 μ m or more) to reinforce the adhesive contact considering the thickness of the termination or capacitor (20-70 μ m) and the land pattern (30-35 μ m).

● Mechanical shock of the chip placer

When the positioning claws and pick-up nozzle are worn, the load is applied to the chip while positioning is concentrated in one position, thus causing cracks, breakage, faulty positioning accuracy, etc. Careful checking and maintenance are necessary to prevent unexpected trouble.

An excessively low bottom dead point of the suction nozzle imposes great force on the chip during mounting, causing cracked chips. Please set the suction nozzle's bottom dead point on the upper surface of the board.

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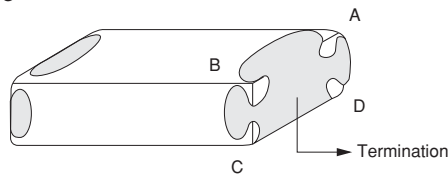
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3. Soldering

(1) Limit of losing effective area of the terminations and conditions needed for soldering.

Depending on the conditions of the soldering temperature and/or immersion (melting time), effective areas may be lost in some parts of the terminations.

To prevent this, be careful in soldering so that any possible loss of the effective area on the terminations will securely remain at a maximum of 25% on all edge length A-B-C-D-A of part with A, B, C, D, shown in the Figure below.



(2) Flux Application

- An excessive amount of flux generates a large quantity of flux gas, causing deteriorated solderability. So apply flux thinly and evenly throughout. (A foaming system is generally used for flow soldering.)
- Flux containing too high a percentage of halide may cause corrosion of the outer electrodes without sufficient cleaning. Use flux with a halide content of 0.2% max.
- Do not use strong acidic flux.
- Do not use water-soluble flux.*
(*Water-soluble flux can be defined as non rosin type flux including wash-type flux and non-wash-type flux.)

(3) Solder

The use of Sn-Zn based solder will deteriorate the reliability of the MLCC.

Please contact our sales representative or product engineers on the use of Sn-Zn based solder in advance.

4. Cleaning

Please confirm there is no problem in the reliability of the product beforehand when cleaning it with the intended equipment.

The residue after cleaning it might cause a decrease in the surface resistance of the chip and the corrosion of the electrode part, etc. As a result it might cause reliability to deteriorate. Please confirm beforehand that there is no problem with the intended equipment in ultrasonic cleansing.

5. Resin Coating

Please use it after confirming there is no influence on the product with the intended equipment before the resin coating and molding.

A cracked chip might be caused at the cooling/heating cycle by the amount of resin spreading and/or bias thickness.

The resin for coating and molding must be selected as the stress is small when stiffening and the hygroscopic is low as possible.